

WHAT IS CLAIMED IS:

1 1. An apparatus for socketing and testing integrates
2 circuits comprising:

3 an air machine; and

4 a housing comprising (i) a printed circuit board that
5 is operable to receive a device under test, and (ii) a controller
6 that is operable to control testing of the received device under
7 test;

8 wherein said air machine is associable with said
9 housing to form an at least substantially air-tight chamber
10 ensconcing the received device under test.

1 2. The apparatus as set forth in Claim 1 wherein said
2 housing further comprises a power supply.

1 3. The apparatus as set forth in Claim 1 wherein said
2 printed circuit board is circular shaped.

1 4. The apparatus as set forth in Claim 3 wherein said
2 housing further comprises I/O connectors that are placed
3 circumferentially and symmetrically near the edge of the printed
4 circuit board.

1 5. The apparatus as set forth in Claim 3 wherein said
2 printed circuit board comprises a leadless socket.

1 6. The apparatus as set forth in Claim 5 wherein said
2 leadless socket is operable to receive the device under test in
3 the center of the Printed circuit board.

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1 7. A method of operating an apparatus for socketing and
2 testing integrated circuits, said apparatus comprising an air
3 machine and a housing, said housing comprising a printed circuit
4 board and a controller, said method comprising the steps of
5 (i) receiving a device under test, and (ii) associating said air
6 machine with said housing to form an at least substantially air-
7 tight chamber ensconcing the received device under test.

1 8. The method as set forth in Claim 7 wherein said housing
2 further comprises a power supply, and said method comprising the
3 step of powering on the apparatus.

1 9. The method as set forth in Claim 7 wherein said printed
2 circuit board is circular shaped, and said method comprising the
3 step of controlling testing of the received device under test
4 with said controller.

1 10. The method as set forth in Claim 9 wherein said housing
2 further comprises I/O connectors that are placed
3 circumferentially and symmetrically near the edge of the printed
4 circuit board.

1 11. The method as set forth in Claim 9 wherein said printed
2 circuit board comprises a leadless socket.

1 12. The method as set forth in Claim 11 wherein said
2 leadless socket is operable to receive the device under test in
3 the center of the Printed circuit board.

1 13. An apparatus for socketing and testing integrated
2 circuits comprising:

3 an air machine; and

4 a housing comprising (i) a universal printed circuit
5 board that is operable to receive a device under test, (ii) a
6 controller that is operable to control testing of the received
7 device under test, and (ii) a power supply;

8 wherein said air machine is associable with said
9 housing to form an at least substantially air-tight chamber
10 ensconcing the received device under test.

1 14. The apparatus as set forth in Claim 13 wherein said
2 power supply is a battery.

1 15. The apparatus as set forth in Claim 13 wherein said
2 universal printed circuit board is circular shaped.

1 16. The apparatus as set forth in Claim 15 wherein said
2 housing further comprises I/O connectors that are placed
3 circumferentially and symmetrically near the edge of the
4 universal printed circuit board.

1 17. The apparatus as set forth in Claim 15 wherein said
2 printed circuit board comprises a leadless socket.

1 18. The apparatus as set forth in Claim 17 wherein said
2 leadless socket is operable to receive the device under test in
3 the center of the printed circuit board.

1 19. The apparatus as set forth in Claim 13 wherein the
2 device under test is one of a RF integrated circuit and a
3 high-frequency integrated circuit.

1 20. The apparatus as set forth in Claim 17 wherein said
2 leadless socket is self-registering.